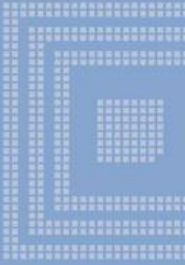




ASE GROUP



# 日月光集團

## 2015 第二季法人說明會

吳田玉  
集團營運長

2015年7月30日

# 免責聲明



This presentation contains "forward-looking statements" within the meaning of Section 27A of the United States Securities Act of 1933, as amended, and Section 21E of the United States Securities Exchange Act of 1934, as amended, including statements regarding our future results of operations and business prospects. Although these forward-looking statements, which may include statements regarding our future results of operations, financial condition or business prospects, are based on our own information and information from other sources we believe to be reliable, you should not place undue reliance on these forward-looking statements, which apply only as of the date of this press release. The words "anticipate," "believe," "estimate," "expect," "intend," "plan" and similar expressions, as they relate to us, are intended to identify these forward-looking statements in this press release. Our actual results of operations, financial condition or business prospects may differ materially from those expressed or implied in these forward-looking statements for a variety of reasons, including risks associated with cyclicity and market conditions in the semiconductor or electronic industry; changes in our regulatory environment, including our ability to comply with new or stricter environmental regulations and to resolve environmental liabilities; demand for the outsourced semiconductor packaging, testing and electronic manufacturing services we offer and for such outsourced services generally; the highly competitive semiconductor or manufacturing industry we are involved in; our ability to introduce new technologies in order to remain competitive; international business activities; our business strategy; our future expansion plans and capital expenditures; the strained relationship between the Republic of China and the People's Republic of China; general economic and political conditions; the recent global economic crisis; possible disruptions in commercial activities caused by natural or human-induced disasters; fluctuations in foreign currency exchange rates; and other factors. For a discussion of these risks and other factors, please see the documents we file from time to time with the Securities and Exchange Commission, including our 2014 Annual Report on Form 20-F filed on March 18, 2015.



# 日月光2015上半年度營運概況



## ● 艱困環境及混合消息

- iOS 對 Android 陣營消長, 個人電腦需求疲軟, 汽車/工業生意穩定
- 存貨控制極度保守
- 整併對代工封測有正向影響(汰除過時資產, 對新產能有更多需求)

## ● 上半年合併營收達歷史新高

- 合併營收較去年上半年營收年成長 15%
- 合併系統級封裝營收為去年上半年營收的三倍
  - ◆ 系統級封裝占合併營收比例: 7% 到 19% (1H14到1H15)
- 覆晶封裝, 凸塊及晶圓級封裝營收較去年上半年營收年成長 11%
  - ◆ 市占率增加及封裝種類轉換

註: \*營收年成長率係依照美金計算.

# 系統級封裝思維模式



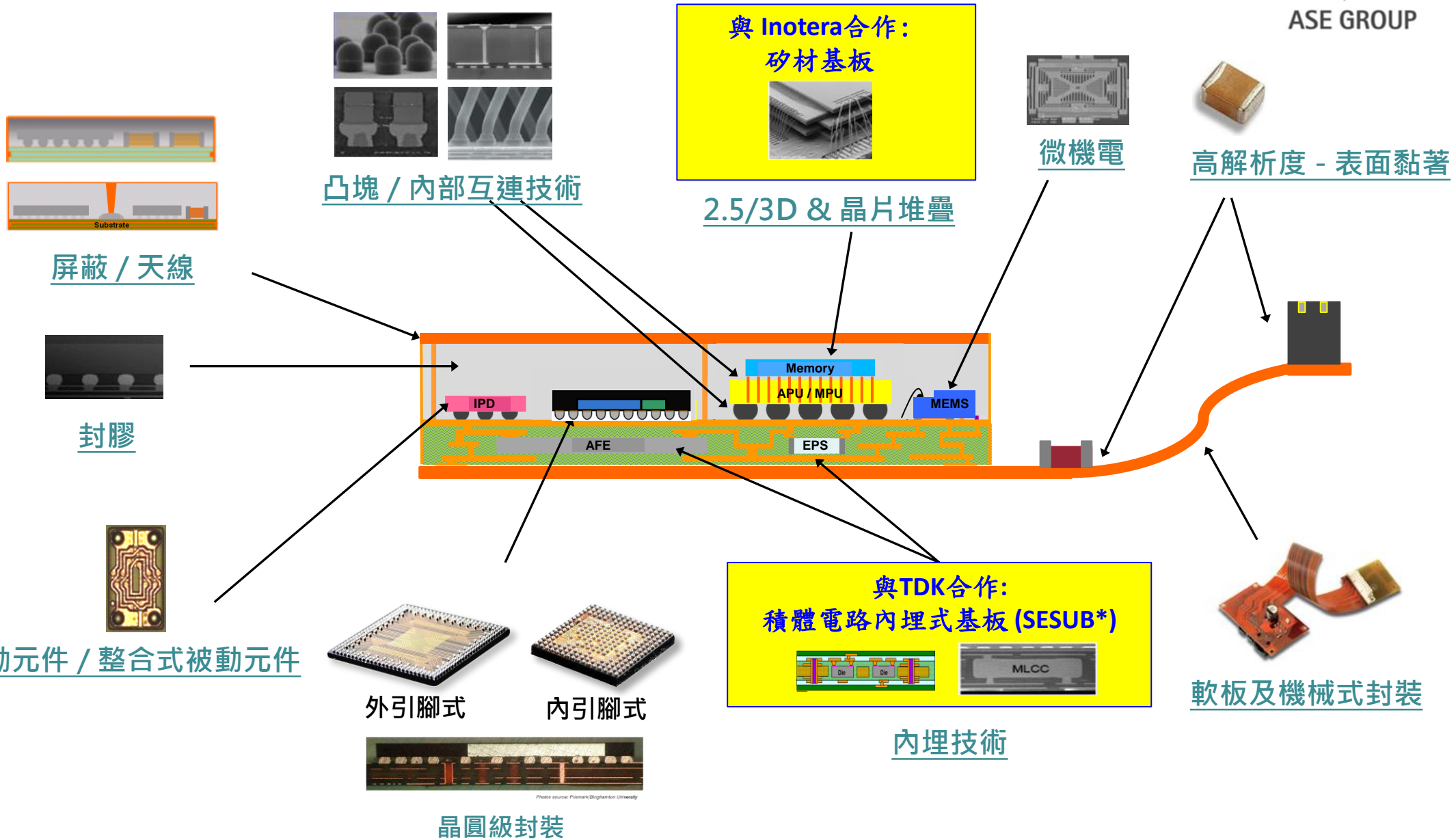
- 整合異質零件及功能性以達成最有效率的尺寸規格及成本
- 與系統商，集成電路，傳感器，微機電，光纖，記憶體，基板，材料及設備供應商在設計到生產上相互合作
- 創造標準平台與產能，流程，以及產權以支持系統級封裝轉換
- 真正國際化，真正業界合作，真正垂直整合



# 添加差異化到系統級封裝工具箱



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\*SESUB為TDK的商標或註冊商標

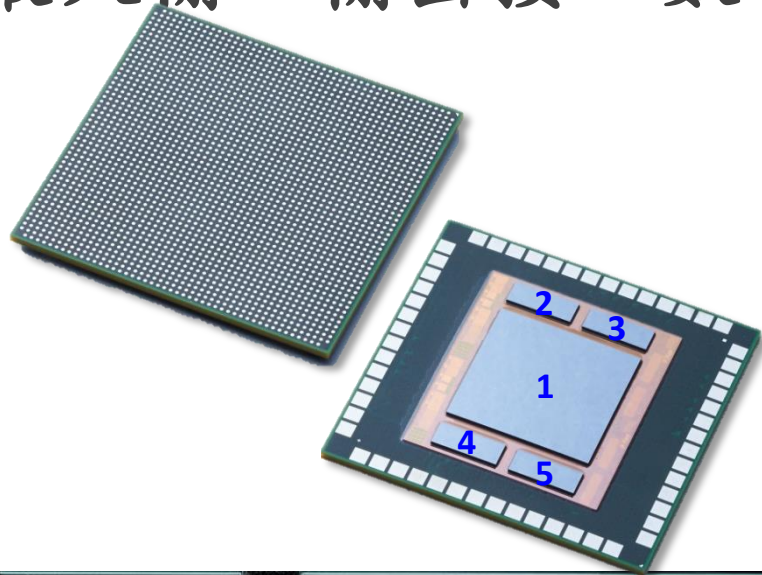
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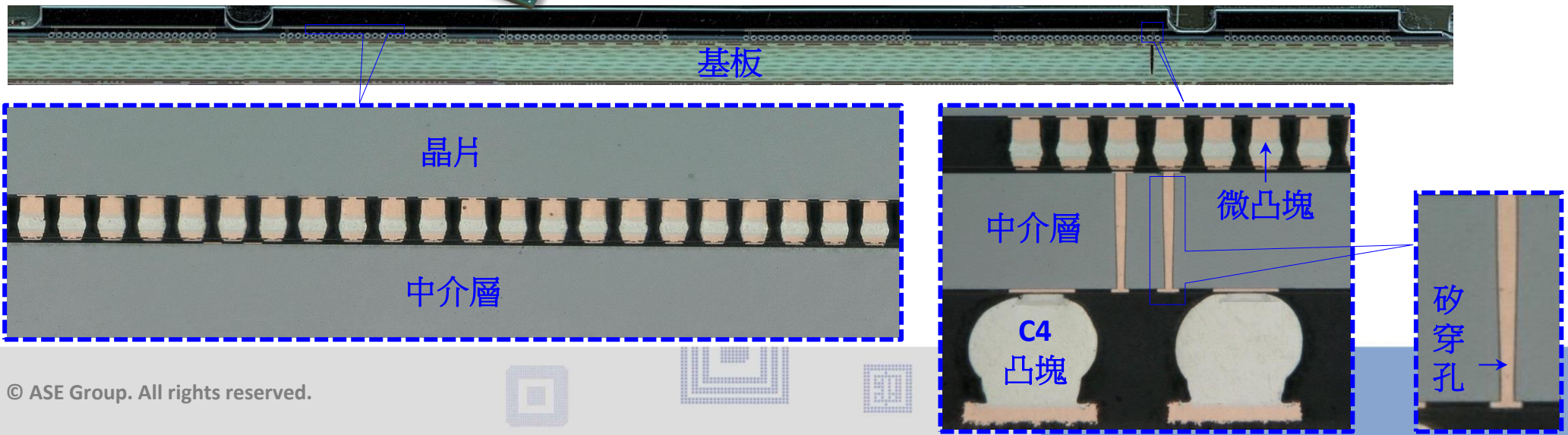


## 2.5D 晶片：摩爾定律的替代方案

- 全球首度量產**2.5D FCBGA**
- 最大輸入輸出接口數為現有**FCBGA**封裝的**20倍**



- 封裝類型：2.5D IC, 50 x 50 x 1.7 mm<sup>3</sup> 2, 397L
- 中介層晶片大小：24 x 36 mm<sup>2</sup>
- 晶片1大小：22.2 x 22.2 mm<sup>2</sup>
- 晶片 2, 3, 4 & 5 大小：4.2 x 10.2 mm<sup>2</sup>
- 微凸塊間距& 接點：40 μm & > 135,000
- C4凸塊間距& 接點：170 μm & 11,000



# 2015 下半年業績展望

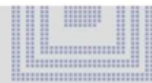
- 即使市場能見度低，仍保持謹慎樂觀
- 預期下半年半導體封測及電子代工服務營收逐季成長
- 繼續透過現有及全新的專案建構系統級封裝成長動能
- 資本支出維持在現有步調
  - 1H15資本支出：美金\$353百萬元\*

\* 註： 資本支出金額僅為機器設備



謝謝

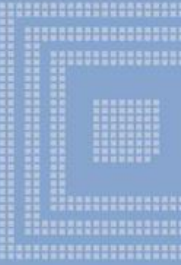
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# 日月光半導體 2015第二季法人說明會

董宏思  
財務長  
日月光半導體  
2015年7月30日

# Safe Harbor Notice



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# 合併綜合損益表

與上一季比較

(未經會計師查核)



(新台幣百萬元)	Q2 / 2015	%	Q1 / 2015	%	季變化
營業收入淨額:					
封裝	28,618	40.8%	29,321	45.3%	-2%
測試	6,231	8.9%	6,180	9.6%	1%
材料直接銷售	839	1.2%	861	1.3%	-3%
電子代工服務	34,534	49.2%	28,300	43.8%	22%
其它	0	0.0%	0	0.0%	
營業收入淨額合計	70,222	100.0%	64,662	100.0%	9%
營業毛利	11,566	16.5%	12,313	19.0%	-6%
營業淨利 (淨損)	5,409	7.7%	6,292	9.7%	-14%
稅前淨利 (淨損)	5,400	7.7%	5,506	8.5%	-2%
所得稅利益 (費用)	(1,596)	-2.3%	(856)	-1.3%	
非控制權益	(152)	-0.2%	(181)	-0.3%	
歸屬於本公司業主之淨利	3,652	5.2%	4,469	6.9%	-18%
基本每股盈餘 (新台幣元)	0.48		0.58		-17%
稀釋每股盈餘 (新台幣元)	0.43		0.56		-23%
EBITDA	13,369	19.0%	13,470	20.8%	-1%



# 合併綜合損益表

與去年同期比較

(未經會計師查核)



(新台幣百萬元)	Q2 / 2015	%	Q2 / 2014	%	年變化
營業收入淨額:					
封裝	28,618	40.8%	30,641	52.3%	-7%
測試	6,231	8.9%	6,600	11.3%	-6%
材料直接銷售	839	1.2%	873	1.5%	-4%
電子代工服務	34,534	49.2%	20,501	35.0%	68%
其它	0	0.0%	0	0.0%	
營業收入淨額合計	70,222	100.0%	58,615	100.0%	20%
營業毛利	11,566	16.5%	12,610	21.5%	-8%
營業淨利 (淨損)	5,409	7.7%	6,615	11.3%	-18%
稅前淨利 (淨損)	5,400	7.7%	6,065	10.3%	-11%
所得稅利益 (費用)	(1,596)	-2.3%	(821)	-1.4%	
非控制權益	(152)	-0.2%	(138)	-0.2%	
歸屬於本公司業主之淨利	3,652	5.2%	5,106	8.7%	-28%
基本每股盈餘 (新台幣元)	0.48		0.66		-27%
稀釋每股盈餘 (新台幣元)	0.43		0.65		-34%
EBITDA	13,369	19.0%	13,125	22.4%	2%



# 綜合損益表 – 半導體封裝測試

與上一季比較

(未經會計師查核)



(新台幣百萬元)	Q2 / 2015	%	Q1 / 2015	%	季變化
營業收入淨額:					
封裝	30,558	81.1%	31,546	81.7%	-3%
測試	6,230	16.5%	6,180	16.0%	1%
材料直接銷售	865	2.3%	861	2.2%	0%
其它	18	0.0%	18	0.0%	
營業收入淨額合計	37,671	100.0%	38,605	100.0%	-2%
營業毛利	9,504	25.2%	9,995	25.9%	-5%
營業淨利 (淨損)	5,101	13.5%	5,546	14.4%	-8%
稅前淨利 (淨損)	5,229	13.9%	5,230	13.5%	0%
所得稅利益 (費用)	(1,537)	-4.1%	(709)	-1.8%	
非控制權益	(40)	-0.1%	(52)	-0.1%	
歸屬於本公司業主之淨利	3,652	9.7%	4,469	11.6%	-18%
EBITDA	11,620	30.8%	11,937	30.9%	-3%



# 綜合損益表 – 半導體封裝測試

與去年同期比較

(未經會計師查核)



(新台幣百萬元)	Q2 / 2015	%	Q2 / 2014	%	年變化
營業收入淨額:					
封裝	30,558	81.1%	31,792	81.0%	-4%
測試	6,230	16.5%	6,600	16.8%	-6%
材料直接銷售	865	2.3%	874	2.2%	-1%
其它	18	0.0%	0	0.0%	
營業收入淨額合計	37,671	100.0%	39,266	100.0%	-4%
營業毛利	9,504	25.2%	10,599	27.0%	-10%
營業淨利 (淨損)	5,101	13.5%	5,986	15.2%	-15%
稅前淨利 (淨損)	5,229	13.9%	5,794	14.8%	-10%
所得稅利益 (費用)	(1,537)	-4.1%	(650)	-1.7%	
非控制權益	(40)	-0.1%	(38)	-0.1%	
歸屬於本公司業主之淨利	3,652	9.7%	5,106	13.0%	-28%
EBITDA	11,620	30.8%	12,068	30.7%	-4%

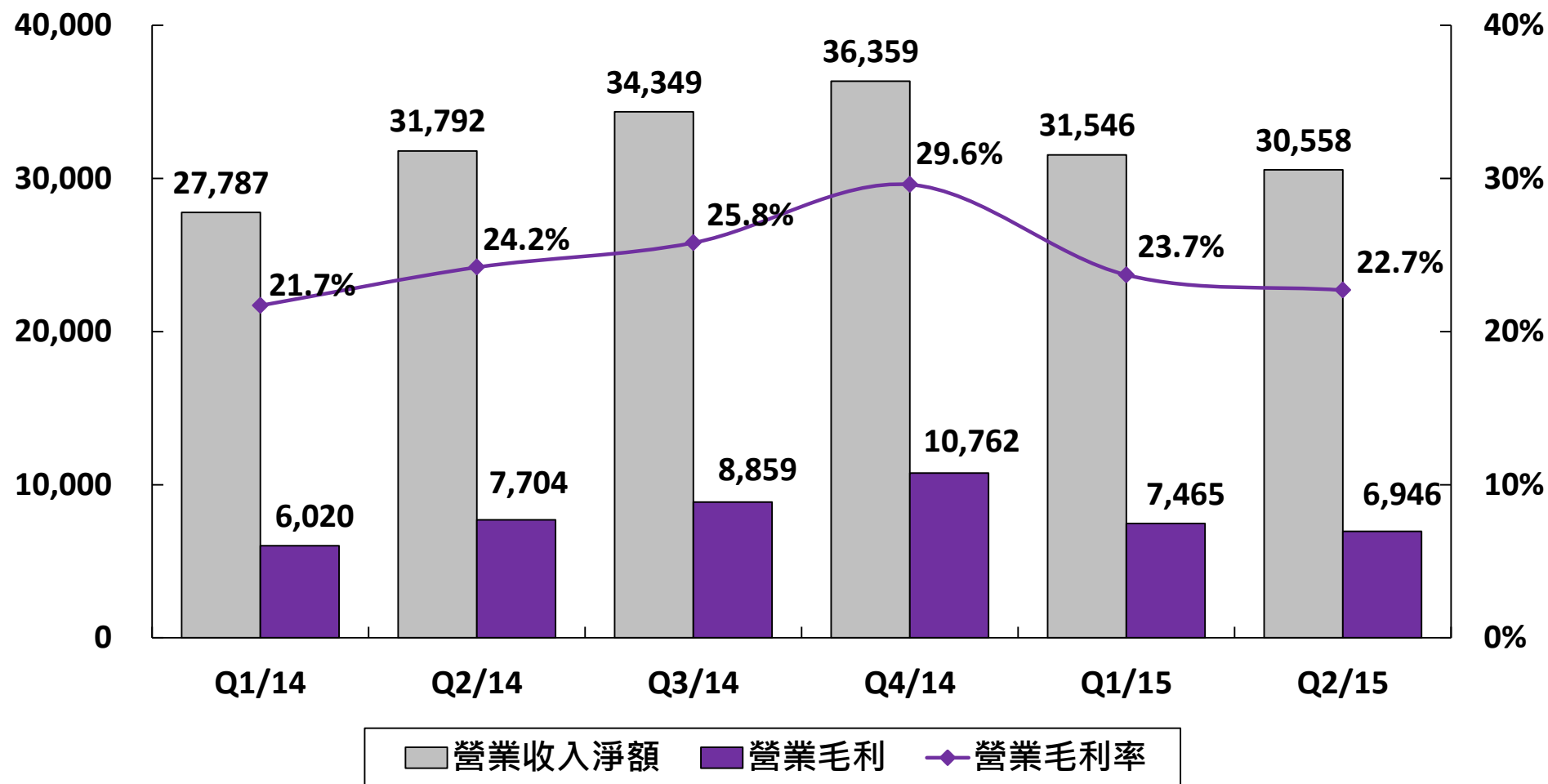




# 封裝業務

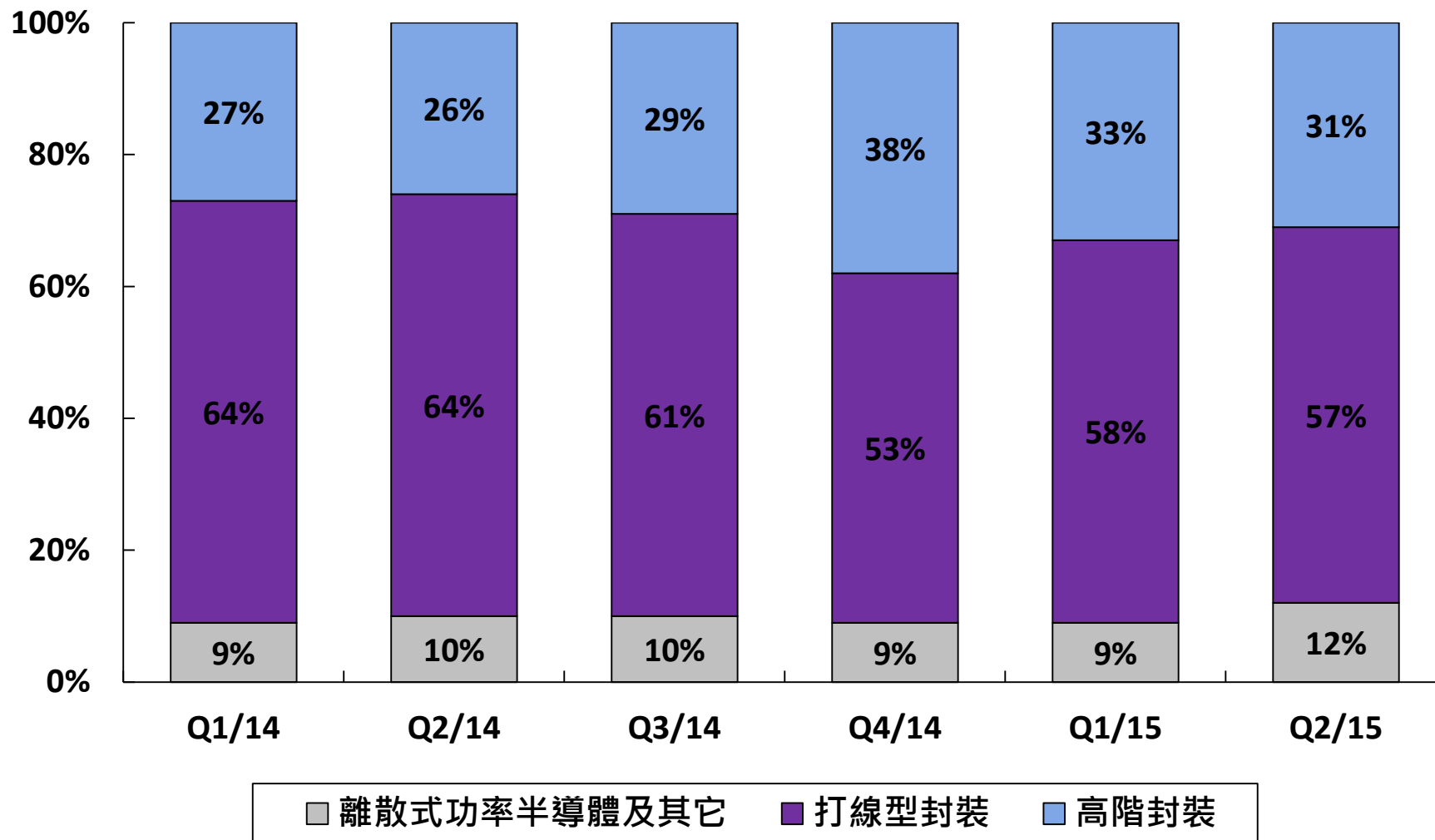


新台幣百萬元



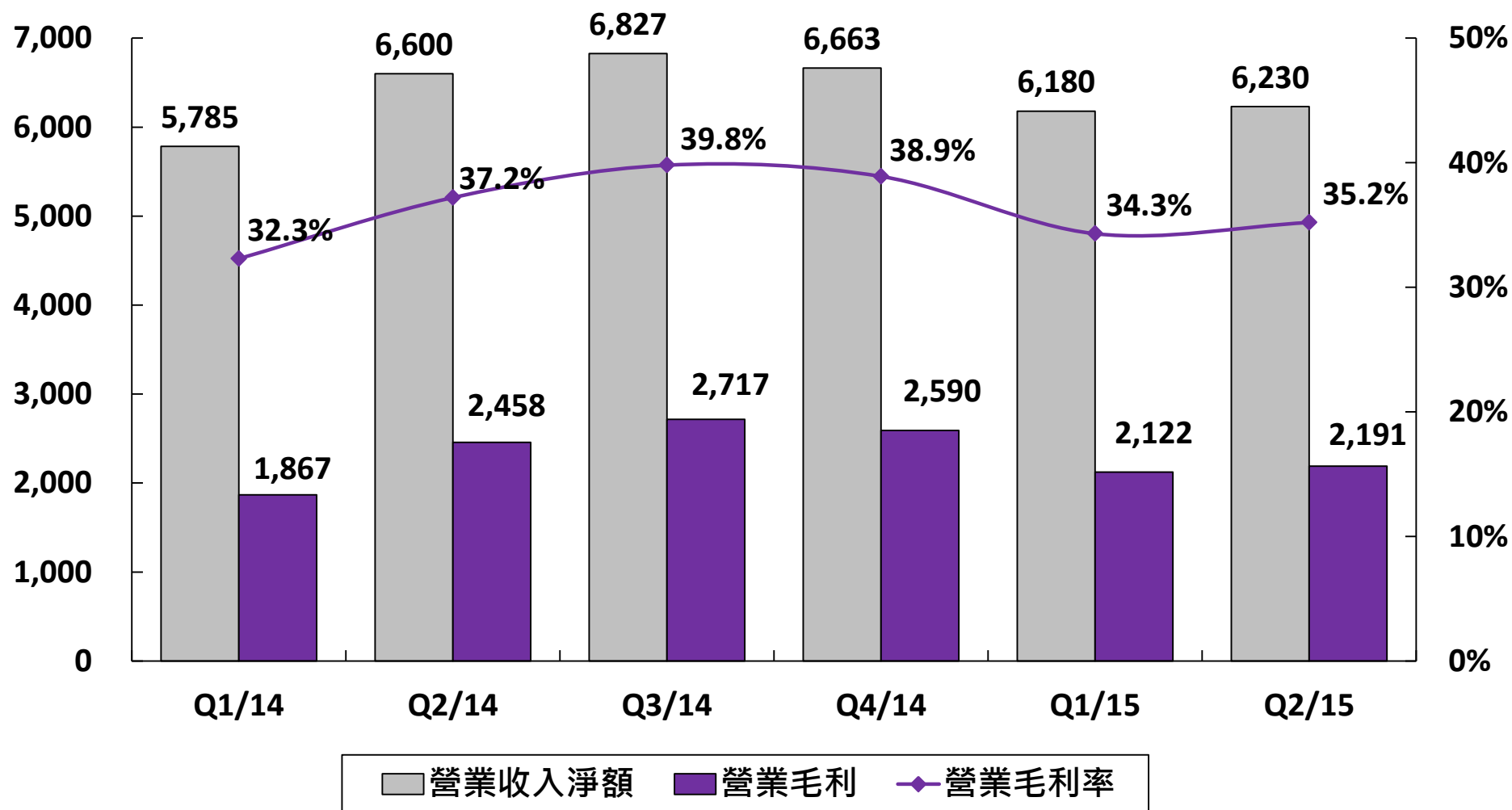
# 封裝業務

產品組合



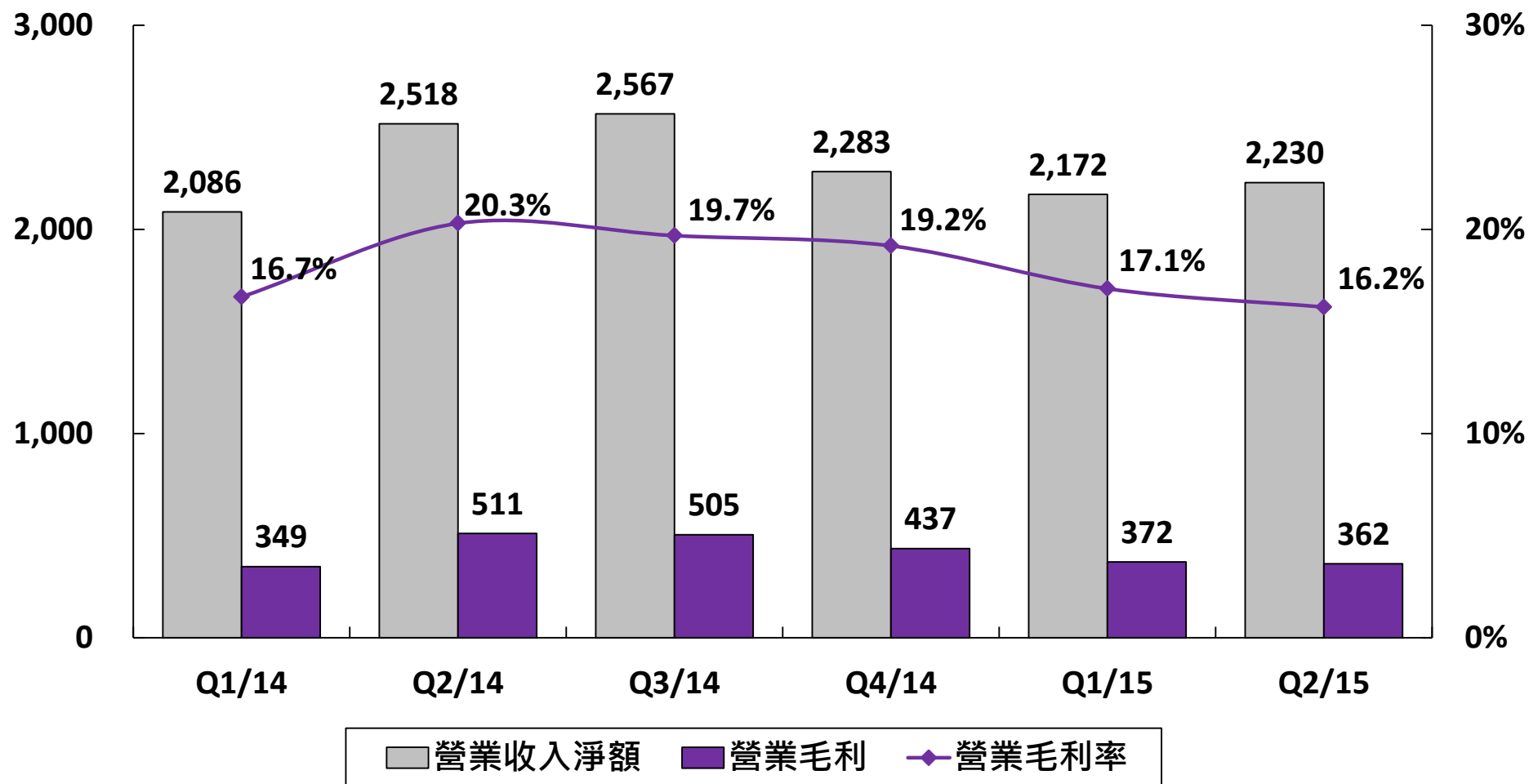
# 測試業務

新台幣百萬元



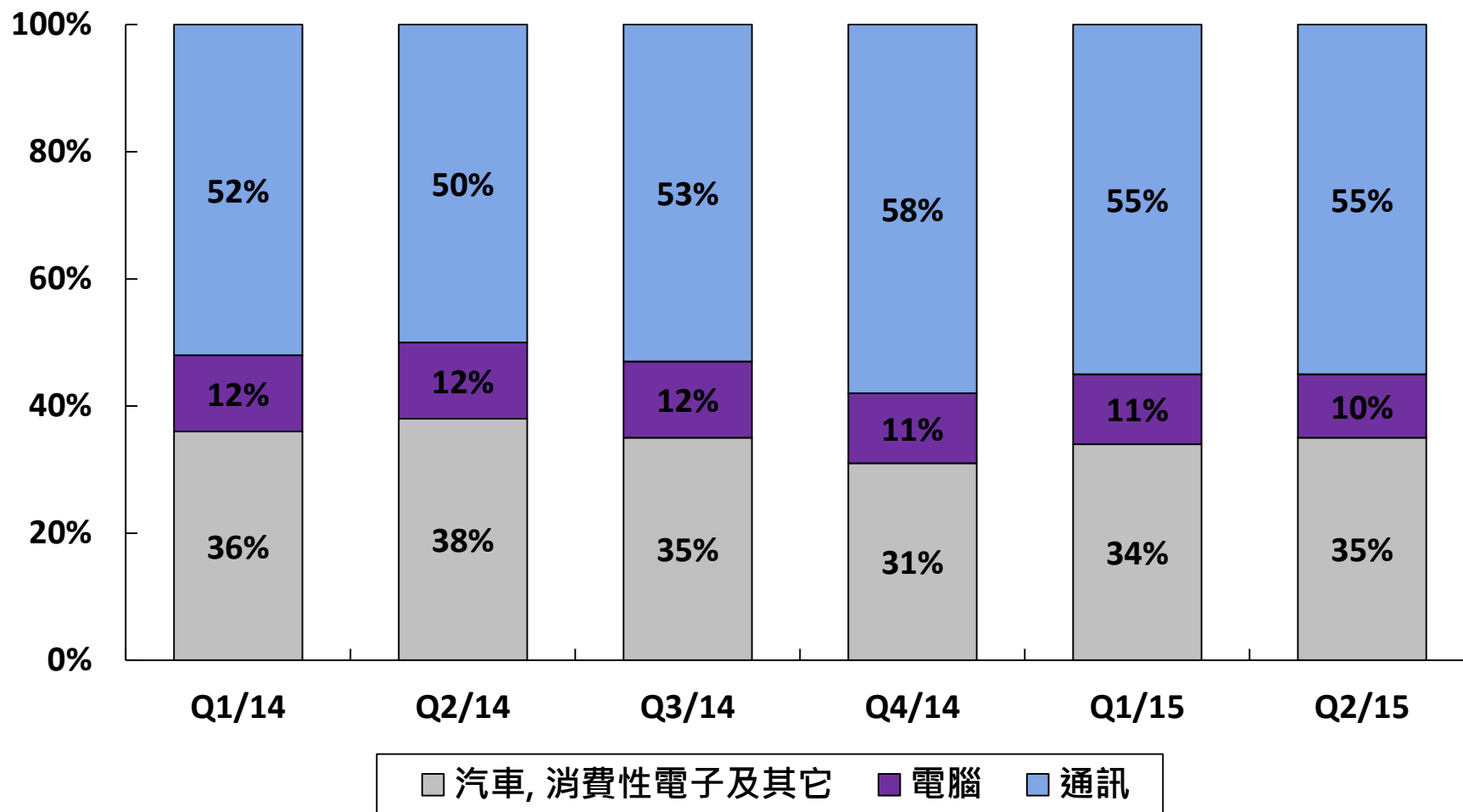
# 材料業務

新台幣百萬元



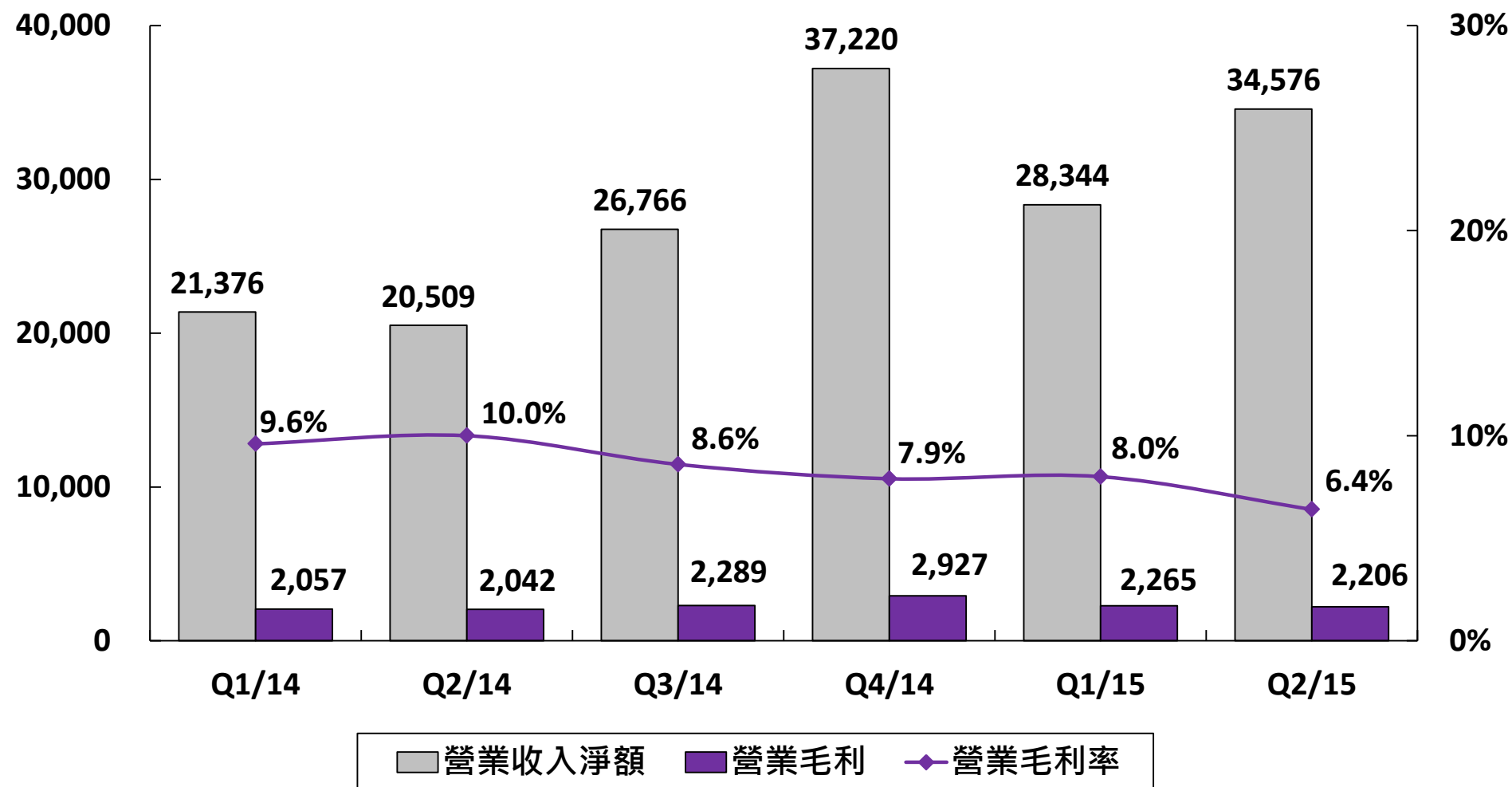
# 半導體封測營收

產品應用別佔比



# 電子代工服務業務

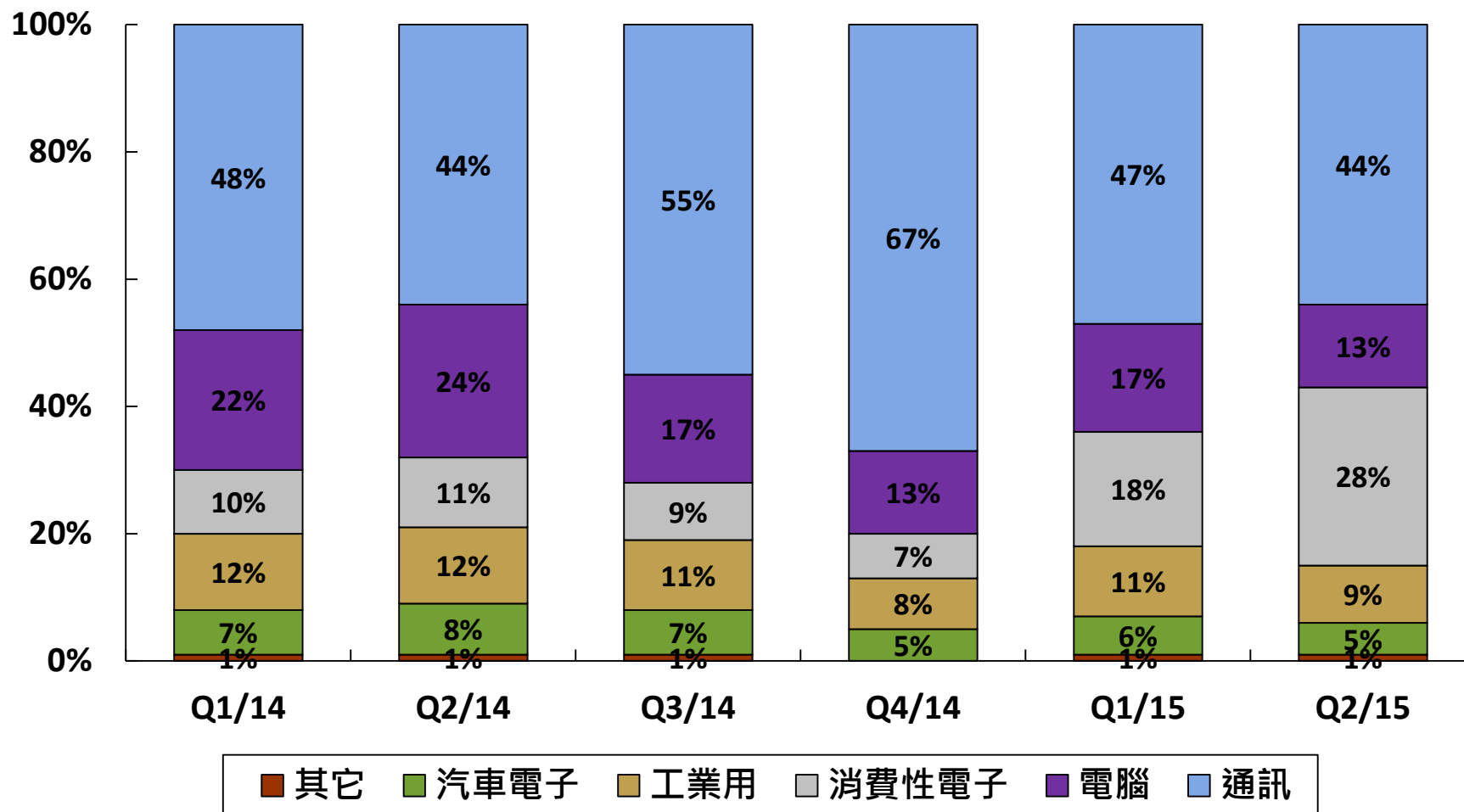
新台幣百萬元





# 電子代工服務業務

產品應用別



# 重要資產負債表項目及財務指標

(未經會計師查核)

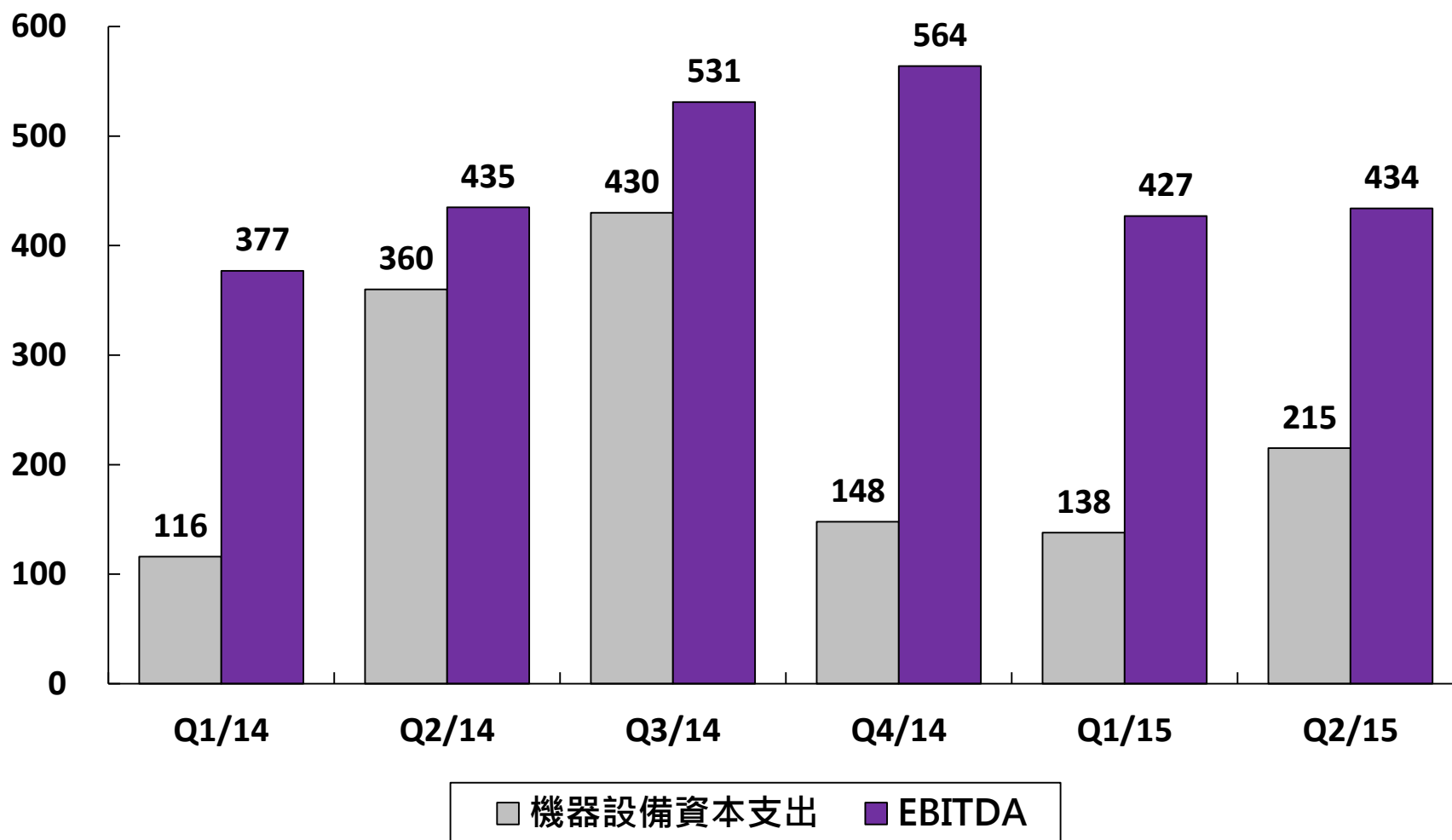


(新台幣百萬元)	2015年6月30日	2015年3月31日	季變化
現金及約當現金	54,175	49,414	9.6%
金融資產 - 流動	4,690	5,510	-14.9%
金融資產 - 非流動及採用權益法之投資	2,280	2,475	-7.9%
不動產、廠房及設備	152,755	150,055	1.8%
資產總計	335,161	322,490	3.9%
短期借款	37,193	36,661	1.5%
一年內到期之長期借款及應付租賃款	1,554	1,151	35.0%
應付公司債	30,867	31,093	-0.7%
長期借款及應付租賃款	22,290	24,751	-9.9%
權益總計 (含非控制權益)	152,688	156,648	-2.5%
當季 EBITDA	13,369	13,470	-0.7%
流動比率	1.34	1.48	
負債權益比率	0.22	0.25	



# 機器設備資本支出及EBITDA

美金百萬元



## 2015年第三季業績展望

根據對當前業務狀況的評估及匯率的假設，日月光公司2015年第三季的業績展望如下：

- 半導體封測事業之產能應持平，產能利用率應成長1%至5%；
- 半導體封測事業之毛利率應與第一季水準相近；
- 電子代工服務生意量應接近4Q14水準；
- 電子代工服務毛利率應小幅下滑。



# Thank You

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